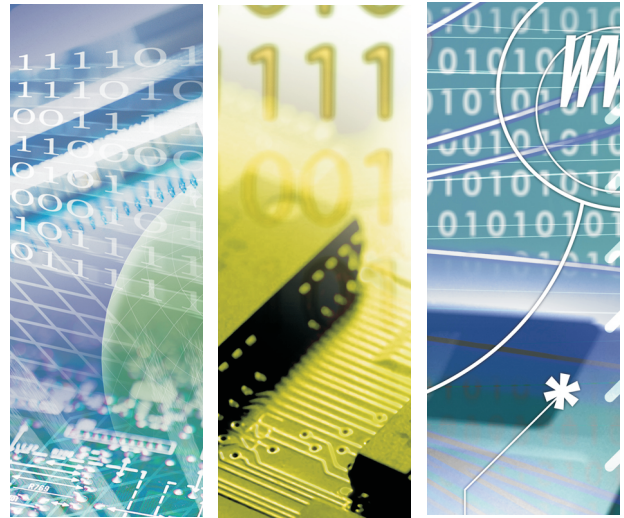




MPE702-Q

3.75G HSPA+ MiniPCI Express Card



MPE702-Q

New Generation of 3.75G Wireless Telecom Speedy Solution

Introduction to Products

Bointec MPE702Q HSPA+ Full size PCI Express Mini card is an embedded module, it can be easily integrated into laptops or other devices for 3G mobile data application offering data, SMS solutions. MPE702Q offers high performance to the user and operates globally on 900/2100MHz bands on HSPA+ and UMTS networks. In areas where HSPA+ service are not available, Bointec MPE702Q still enables reliable and secure data connections over HSPA/UMTS or EDGE/GPRS network.

Features

- Improved power-saving modes
- NDIS/USB driver for Microsoft® Windows® 2000, Windows® XP, Windows® Vista32/64, Windows® 7
- RIL/NDIS/USB driver for devices based on Microsoft® Windows Mobile™ 5.0 and its Successor
- USB driver for Linux2.4.x, Linux2.6.x
- Customer IMEI as variant
- Firmware update via USB
- Windows application PC_SUITE Auto-installation
- Simple, easy deployment
- RoHS compliant

MPE702Q Specification		
Band	GSM(Quad-Band)	850/900/1800/1900 MHz
	HSPA+/UMTS	900/2100MHz
Transmission Speed	Uplink	up to 5.76 Mbps
	Downlink	up to 21 Mbps
Data Devices	EDGE (E-GPRS) (multi-slot class 12)	<ul style="list-style-type: none"> EDGE class 12: Max. 237 kbps (DL), Max. 118 kbps (UL) Mobile station class B Modulation and coding scheme MCS 1-9
	GPRS (multi-slot class 12)	<ul style="list-style-type: none"> GPRS class 12: Max. 85.6 kbps (DL) Max. 42.8 kbps (UL) Mobile station class B Full PBCC support Coding schemes CS 1-4
	UMTS/HSUPA (3GPP release 6)	<ul style="list-style-type: none"> HSPA+: Max. 21 Mbps (DL) Max. 5.76 Mbps (UL) HSDPA Category 6/8/14 supported HSUPA Category 3/4/6 supported Compressed mode according to 3GPP TS25.212 UMTS: Max. 384 kbps (DL) Max. 384 kbps (UL)
	GSM	3GPP release 99
	SMS (Short Message)	<ul style="list-style-type: none"> Point-to-point MO and MT SMS cell broadcast Text and PDU mode
	CSD data transmission	<ul style="list-style-type: none"> GSM data rate 14.4 kbps, V.110 UMTS data rate 57.6 kbps, V.120 RLP (Non-transparent mode)
	Tx Output Control Standard	<ul style="list-style-type: none"> Class 4 (2 W) for GSM900 Class 3 (0.25 W) for UMTS/HSUPA Class E2 (0.5 W) for EDGE900 Class E2 (0.4 W) for EDGE1800 Class 1 (1 W) for GSM1800
Control	AT commands (Hayes 3GPP TS 27.007 and 27.005)	
SIM Slot	SIM Application Toolkit (release 99)	
Power consumption	Voltage	3.0V~3.6V
	Watts/Current	10W Maximum
	Average Supply Current	< 800mA(HSPA data transfer)
	Sleep mode	<4mA
	Power down	50 μ A
Form Factor	Dimension	51*30*4.5 mm
	Weight	12 g
Temperature	Normal Operation	-20°C to +65°C
	Extremely Operation	-30°C to +75°C
	Storage	-40°C to +85°C
Interface	PCI express mini Card	<ul style="list-style-type: none"> Hirose U.FL-R-SMT 50 antenna connector PCI Express® Mini Card Interface (Revision 1.2) USB 2.0 high speed UICC/SIM card interface 3 V, 1.8 V Flying Mode Network status UART GPIOs
Driver	Windows	XP / XP Embedded / CE / Vista / Win7 / Win8
	Linux	Kernel 2.4.24 (later)
	Mac	Mac Operation System



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